7MBR50XKB065-50

IGBT Modules

Power Module(X series)
650V / 50A / PIM

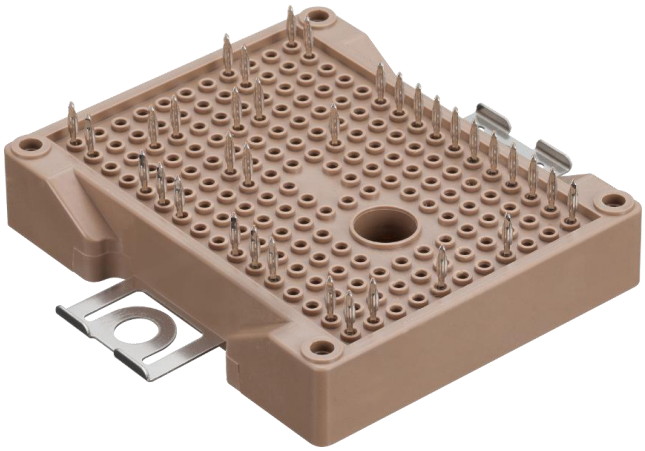
■ Feactures

Low $V_{CE(sat)}$
Compact Package
P.C.Board Mount Module
Converter Diode Bridge Dynamic Brake Circuit
RoHS compliant Product

■ Applications

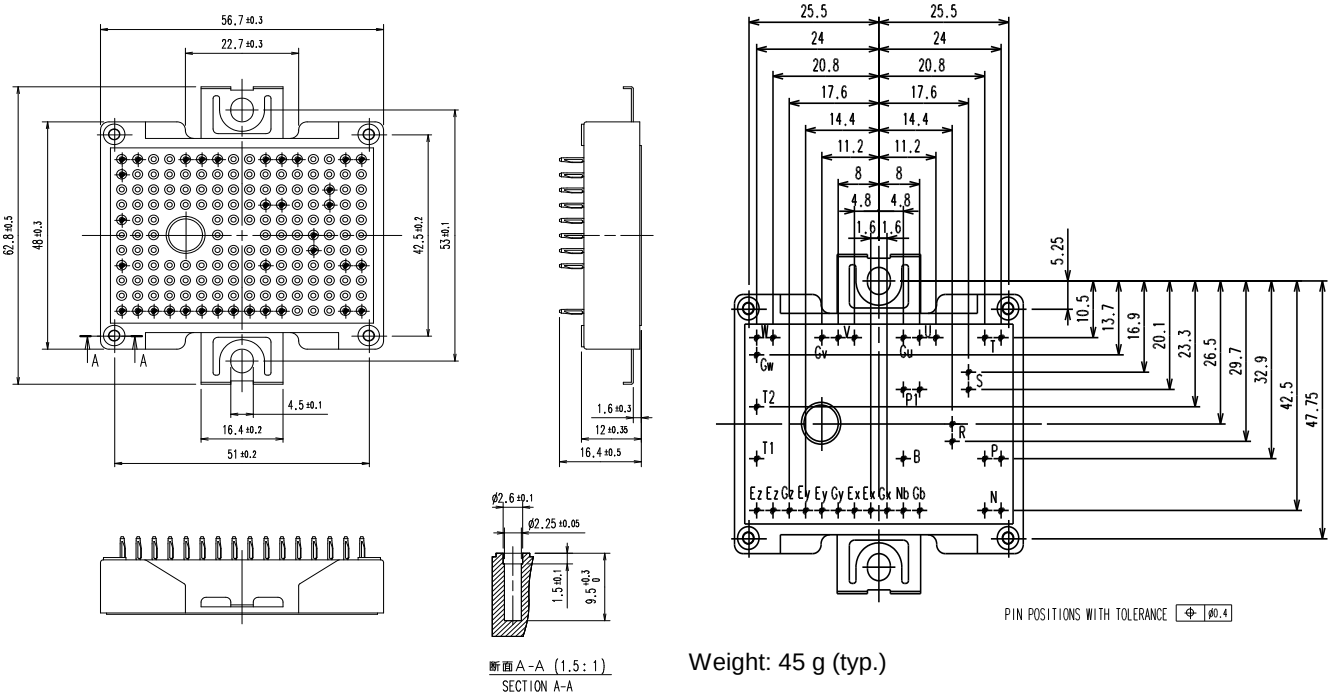
Inverter for Motor Drive
AC and DC Servo Drive Amplifier
Uniterruptible Power Supply

■ Typical appearance



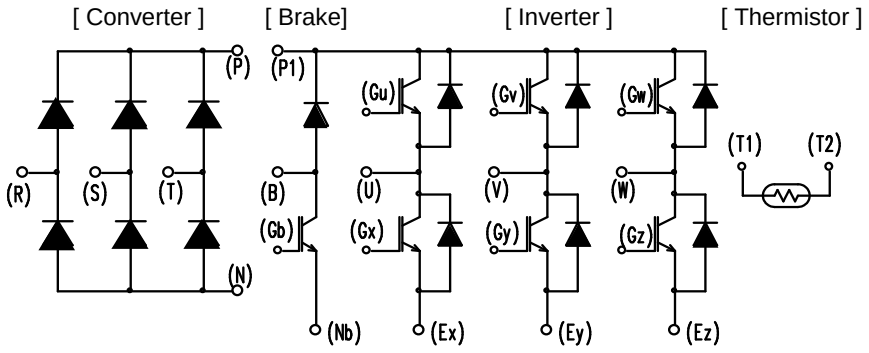
■ Outline drawing (Unit : mm)

shows theoretical dimension.
( ) shows reference dimension.



Weight: 45 g (typ.)

■ Equivalent circuit



■ Maximum ratings (at T_c = 25°C unless otherwise specified)

	Items	Symbols	Conditions		Maximum ratings	Units
Inverter	Collector-emitter voltage, gate-emitter short-circuited	V_{CES}			650	V
	Gate-emitter voltage, collector-emitter short-circuited	V_{GES}			±20	V
	Collector current	I_C	Continuous	T_c=100°C	50	A
	Repetitive peak collector current	I_{CRM}	1ms		100	
	Forward current	I_F	Continuous		50	
	Repetitive peak forward current	I_{FRM}	1ms		100	
	Total power dissipation	P_{tot}	1 device		270	W
Brake IGBT	Collector-emitter voltage, gate-emitter short-circuited	V_{CES}			650	V
	Gate-emitter voltage, collector-emitter short-circuited	V_{GES}			±20	V
	Collector current	I_C	Continuous	T_c=100°C	50	A
	Repetitive peak collector current	I_{CRM}	1ms		100	
	Total power dissipation	P_{tot}	1 device		270	W
Brake FWD	Forward current	I_F	Continuous		20	A
	Repetitive peak forward current	I_{FRM}	1ms		40	
	Repetitive peak reverse voltage	V_{RRM}			650	V
Converter	Repetitive peak reverse voltage	V_{RRM}			800	V
	Average output current	I_O	Three-phase full wave rectified	T_c=80°C	50	A
	Surge forward current (Non-Repetitive) (*1)	I_{FSM}	t=10ms, Half sine wave form	T_{vj}=25°C	535	A
				T_{vj}=150°C	470	
	I^2t (Non-Repetitive) (*1)	I^2t		T_{vj}=25°C	1445	A^2s
				T_{vj}=150°C	1115	
Virtual Junction temperature		T_{vj}	Inverter, Brake		175	°C
			Converter		150	
Operating Virtual junction temperature (under switching conditions)		T_{vjop}	Inverter, Brake		175	
			Converter		150	
Case temperature		T_c			125	
Storage temperature		T_{stg}			-40 ~ 125	
Isolation voltage	between terminals and copper base (*2) between thermistor and others (*3)	V_{isol}	A.C. : 1min.		2500	Vrms
Screw torque (*4)	Mounting torque of screws to heat sink	M_s	M4		1.7	N·m

(*1) T_{vj} : Temperature at test start.
(*2) All terminals should be connected together during the test.
(*3) Two thermistor terminals should be connected together, other terminals should be connected together and shorted to base plate during the test.
(*4) Recommendable value : Mounting 1.3 ~ 1.7 N·m (M4)

■ Electrical characteristics (at T_{vj} = 25°C unless otherwise specified)

	Items	Symbols	Conditions		Characteristics min.	Characteristics typ.	Characteristics max.	Units
Inverter	Collector-emitter cut-off current, gate-emitter short-circuited	I_{CES}	V_{GE} = 0V V_{CE} = 650V		-	-	50	μA
	Gate leakage current, collector-emitter short-circuited	I_{GES}	V_{CE} = 0V V_{GE} = +20/-20V		-	-	100	nA
	Gate-Emitter threshold voltage	$V_{GE(th)}$	V_{CE} = 20V I_C = 50mA		6.0	6.5	7.0	V
	Collector-Emitter saturation voltage	$V_{CE(sat)}$ (terminal)	V_{GE} = 15V I_C = 50A	T_{vj}=25°C	-	1.60	2.10	V
		$V_{CE(sat)}$ (chip)		T_{vj}=25°C	-	1.30	1.75	
				T_{vj}=125°C	-	1.45	-	
				T_{vj}=150°C	-	1.50	-	
				T_{vj}=175°C	-	1.55	-	
	Internal Gate resistance	r_g	-		-	0	-	Ω
	Capacitance	C_{ies}	V_{CE} = 10V, V_{GE} =0V, f = 1MHz		-	5.7	-	nF
		C_{oes}			-	0.22	-	
		C_{res}			-	0.08	-	
	Gate charge	Q_G	V_{CC} = 300V V_{GE}=-15 → +15V I_C = 50A		-	410	-	nC
	Forward voltage	V_F (terminal)	I_F = 50A	T_{vj}=25°C	-	1.85	2.35	V
		V_F (chip)		T_{vj}=25°C	-	1.55	2.00	
				T_{vj}=125°C	-	1.50	-	
				T_{vj}=150°C	-	1.50	-	
				T_{vj}=175°C	-	1.45	-	
	Switching time (*1)	$t_{d(on)}$	V_{CC} = 300V I_C,I_F = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.06	-	μs
				T_{vj}=125°C	-	0.06	-	
				T_{vj}=150°C	-	0.06	-	
				T_{vj}=175°C	-	0.06	-	
		t_r	V_{CC} = 300V I_C,I_F = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.02	-	
				T_{vj}=125°C	-	0.02	-	
				T_{vj}=150°C	-	0.03	-	
				T_{vj}=175°C	-	0.03	-	
		$t_{d(off)}$	V_{CC} = 300V I_C,I_F = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.17	-	
				T_{vj}=125°C	-	0.20	-	
				T_{vj}=150°C	-	0.20	-	
				T_{vj}=175°C	-	0.20	-	
		t_f	V_{CC} = 300V I_C,I_F = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.04	-	
				T_{vj}=125°C	-	0.05	-	
				T_{vj}=150°C	-	0.05	-	
				T_{vj}=175°C	-	0.05	-	
	Reverse recovery time	t_{rr}	V_{CC} = 300V I_C,I_F = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.06	-	
				T_{vj}=125°C	-	0.10	-	
				T_{vj}=150°C	-	0.11	-	
				T_{vj}=175°C	-	0.13	-	

(*1) Turn on time (t_{on}) = $t_{d(on)}$ + t_r , Turn off time (t_{off}) = $t_{d(off)}$ + t_f

	Items	Symbols	Conditions		Characteristics min.	Characteristics typ.	Characteristics max.	Units
Inverter	Switching loss (per pulse)	E_{on}	V_{CC} = 300V I_C,I_F = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.58	-	mJ
				T_{vj}=125°C	-	0.91	-	
				T_{vj}=150°C	-	1.01	-	
				T_{vj}=175°C	-	1.12	-	
		E_{off}	V_{CC} = 300V I_C,I_F = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	1.52	-	
				T_{vj}=125°C	-	1.89	-	
				T_{vj}=150°C	-	2.00	-	
				T_{vj}=175°C	-	2.08	-	
		E_{rr}	V_{CC} = 300V I_C,I_F = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.47	-	
				T_{vj}=125°C	-	0.68	-	
				T_{vj}=150°C	-	0.79	-	
				T_{vj}=175°C	-	0.93	-	
Brake	Collector-emitter cut-off current, gate-emitter short-circuited	I_{CES}	V_{GE} = 0V V_{CE} = 650V		-	-	50	μA
	Gate leakage current, collector-emitter short-circuited	I_{GES}	V_{CE} = 0V, V_{GE} = +20/-20V		-	-	100	nA
	Collector-Emitter saturation voltage	$V_{CE(sat)}$ (terminal)	V_{GE} = 15V I_C = 50A	T_{vj}=25°C	-	1.60	2.10	V
		$V_{CE(sat)}$ (chip)		T_{vj}=25°C	-	1.30	1.75	
				T_{vj}=125°C	-	1.45	-	
				T_{vj}=150°C	-	1.50	-	
				T_{vj}=175°C	-	1.55	-	
	Internal Gate resistance	r_g	-		-	0	-	Ω
	Switching time (*1)	$t_{d(on)}$	V_{CC} = 300V I_C = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.06	-	μs
				T_{vj}=125°C	-	0.06	-	
				T_{vj}=150°C	-	0.06	-	
				T_{vj}=175°C	-	0.06	-	
		t_r	V_{CC} = 300V I_C = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.02	-	
				T_{vj}=125°C	-	0.02	-	
				T_{vj}=150°C	-	0.03	-	
				T_{vj}=175°C	-	0.03	-	
		$t_{d(off)}$	V_{CC} = 300V I_C = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.17	-	
				T_{vj}=125°C	-	0.20	-	
				T_{vj}=150°C	-	0.20	-	
				T_{vj}=175°C	-	0.20	-	
		t_f	V_{CC} = 300V I_C = 50A L_s = 30nH V_{GE} = +15/-15 V R_G = 8.2 Ω	T_{vj}=25°C	-	0.04	-	
				T_{vj}=125°C	-	0.05	-	
				T_{vj}=150°C	-	0.05	-	
				T_{vj}=175°C	-	0.05	-	
	Reverse current	I_{RRM}	V_R = 650V		-	-	50	μA
	Forward voltage	V_F (terminal)	I_F = 20A	T_{vj}=25°C	-	1.90	2.40	V
		V_F (chip)	I_F = 20A	T_{vj}=25°C	-	1.60	2.05	
				T_{vj}=125°C	-	1.60	-	
				T_{vj}=150°C	-	1.60	-	
				T_{vj}=175°C	-	1.55	-	
Converter	Reverse current	I_{RRM}	V_R = 800V		-	-	50	μA
	Continuous (direct) forward voltage	V_F	I_F = 50A	terminal	-	1.40	1.90	V
				chip	-	1.10	1.55	
Thermistor	Resistance	R	T = 25°C		-	5000	-	Ω
			T = 100°C		465	495	520	
	B value	B	T = 25/ 50°C		3305	3375	3450	K

(*1) Turn on time (t_{on}) = $t_{d(on)}$ + t_r , Turn off time (t_{off}) = $t_{d(off)}$ + t_f

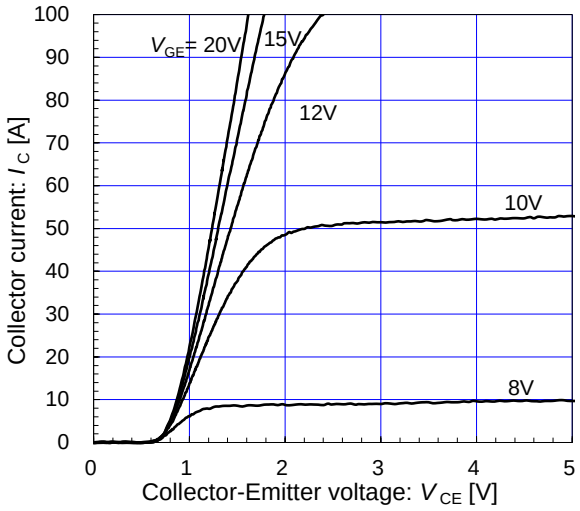
NOTICE:
The external gate resistance (R_G) shown above is one of our recommended value for the purpose of minimum switching loss. However the optimum R_G depends on circuit configuration and/or environment. We recommend that the R_G has to be carefully chosen based on consideration if IGBT module matches design criteria, for example, switching loss, EMC/EMI, spike voltage, surge current and no unexpected oscillation and so on.

■Thermal resistance characteristics

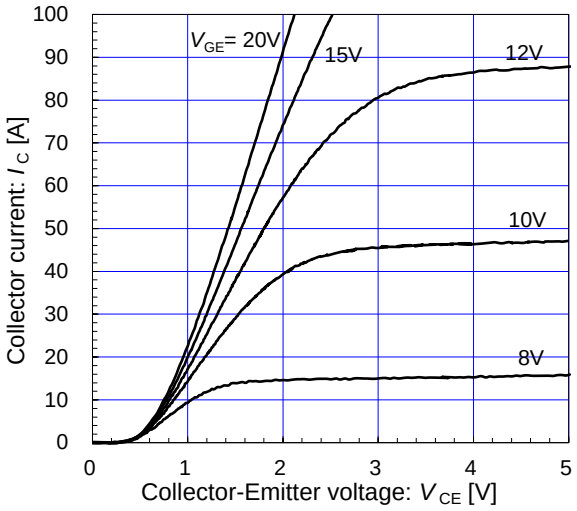
Items	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Thermal resistance junction to case (1 device)	$R_{th(j-c)}$	Inverter IGBT	-	-	0.55	K/W
		Inverter FWD	-	-	0.73	
		Brake IGBT	-	-	0.55	
		Brake FWD	-	-	1.50	
		Converter Diode	-	-	0.58	
Thermal resistance case to heat sink(*1) (1 device)	$R_{th(c-s)}$	Inverter IGBT	-	0.57	-	
		Inverter FWD	-	0.61	-	
		Brake IGBT	-	0.63	-	
		Brake FWD	-	0.71	-	
		Converter Diode	-	0.68	-	

(*1) This is the value which is defined mounting on the additional cooling fin with 1 W/(m・K) thermal grease.

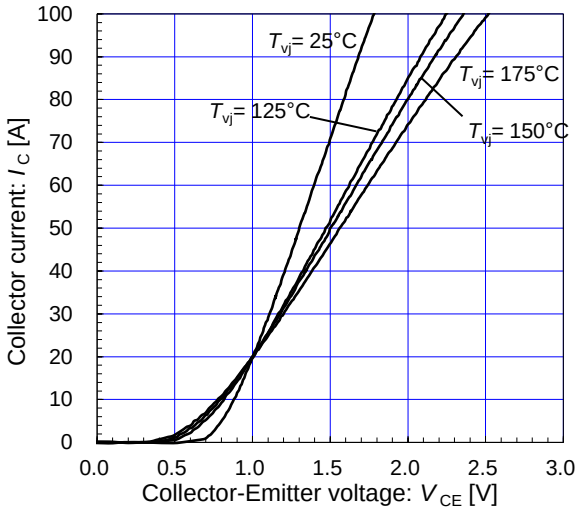
[Inverter]
Collector current vs. Collector-Emitter voltage (typ.)
T_{vj}= 25°C / chip



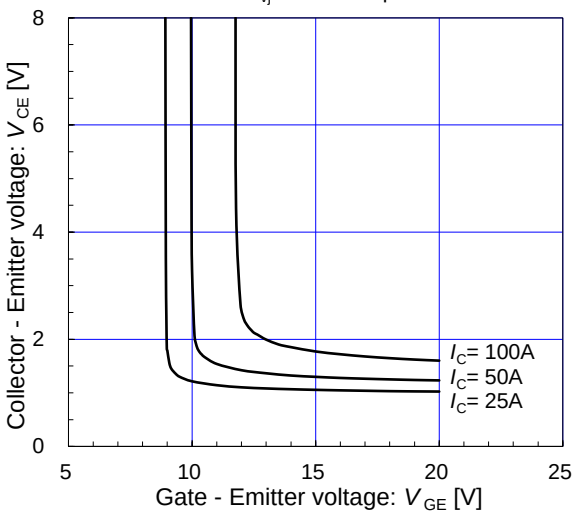
[Inverter]
Collector current vs. Collector-Emitter voltage (typ.)
T_{vj}= 175°C / chip



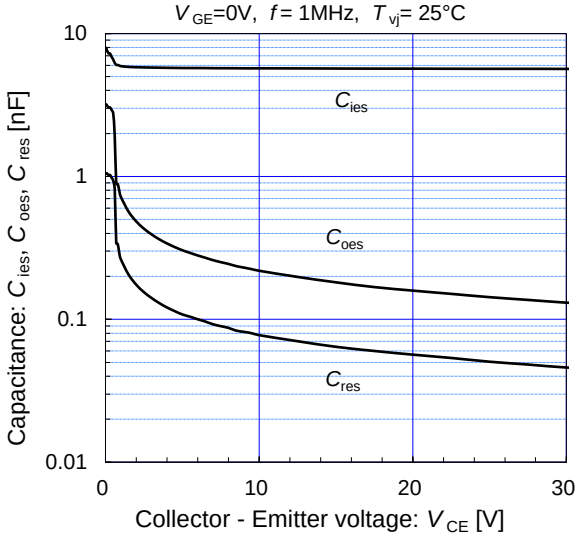
[Inverter]
Collector current vs. Collector-Emitter voltage (typ.)
V_{GE}=15V / chip



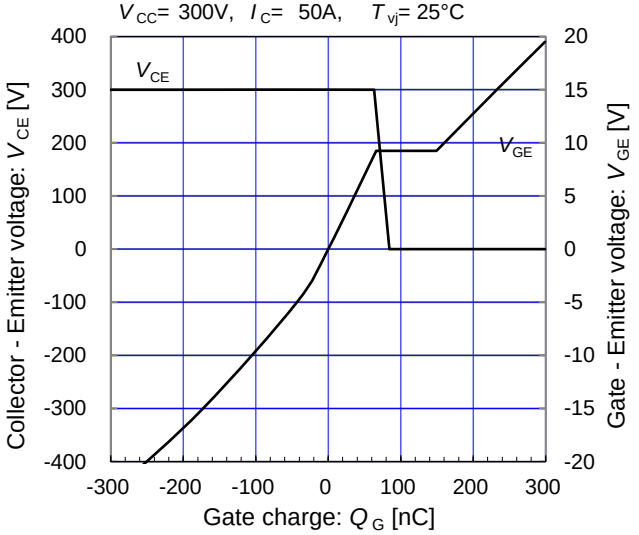
[Inverter]
Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)
T_{vj}= 25°C / chip



[Inverter]
Capacitance vs. Collector-Emitter voltage (typ.)
V_{GE}=0V, f= 1MHz, T_{vj}= 25°C



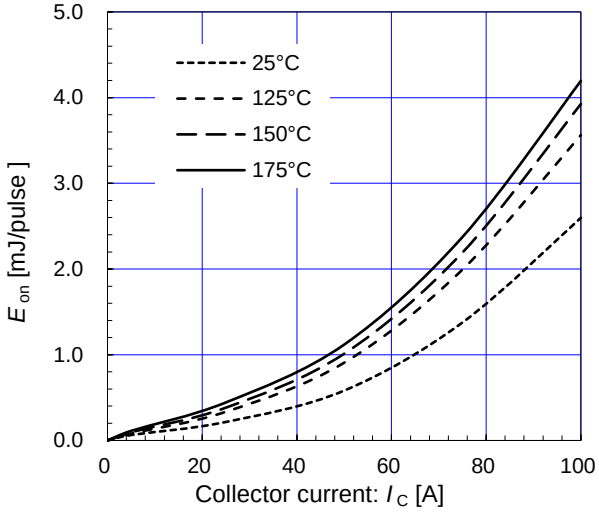
[Inverter]
Dynamic Gate charge (typ.)
V_{CC}= 300V, I_C= 50A, T_{vj}= 25°C



[Inverter]

E_{on} vs. Collector current (typ.)

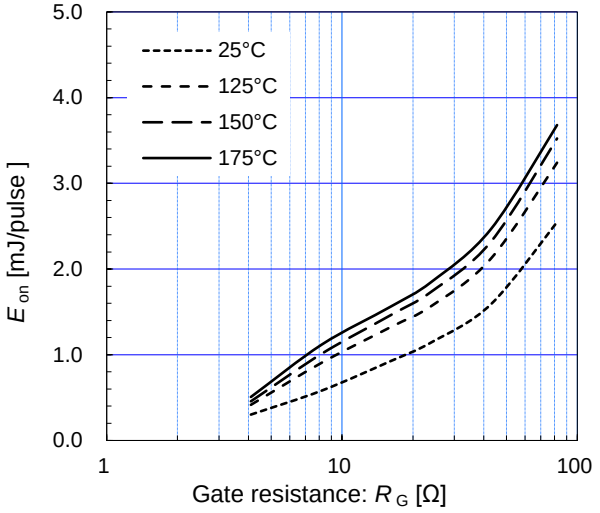
V_{CC}= 300V, V_{GE} = +15/-15 V R_G= 8.2 Ω



[Inverter]

E_{on} vs. Gate resistance (typ.)

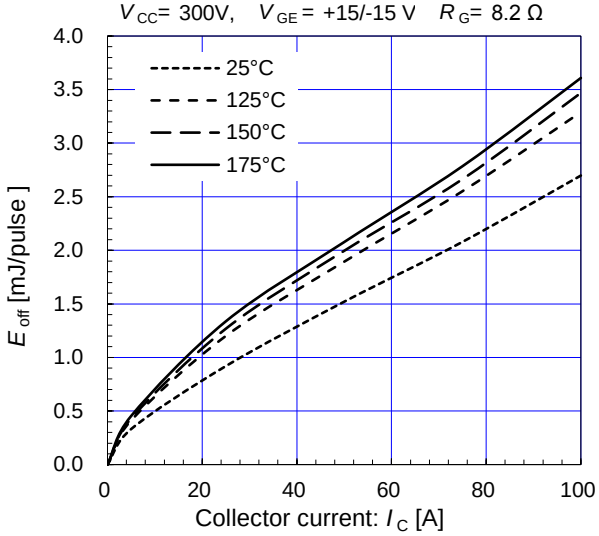
V_{CC}= 300V, V_{GE} = +15/-15 V I_C= 50A



[Inverter]

E_{off} vs. Collector current (typ.)

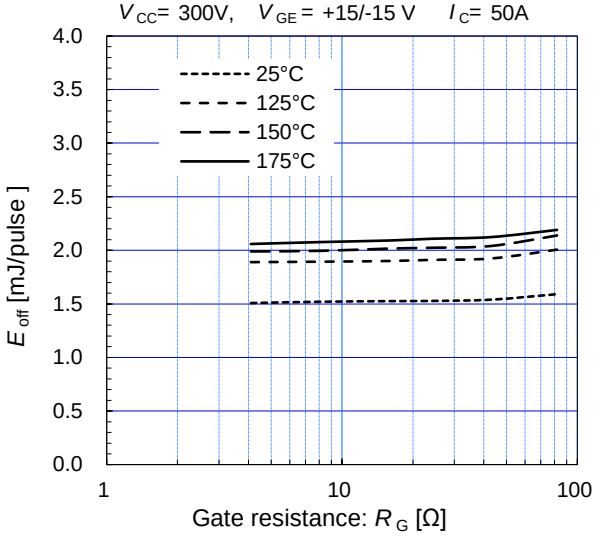
V_{CC}= 300V, V_{GE} = +15/-15 V R_G= 8.2 Ω



[Inverter]

E_{off} vs. Gate resistance (typ.)

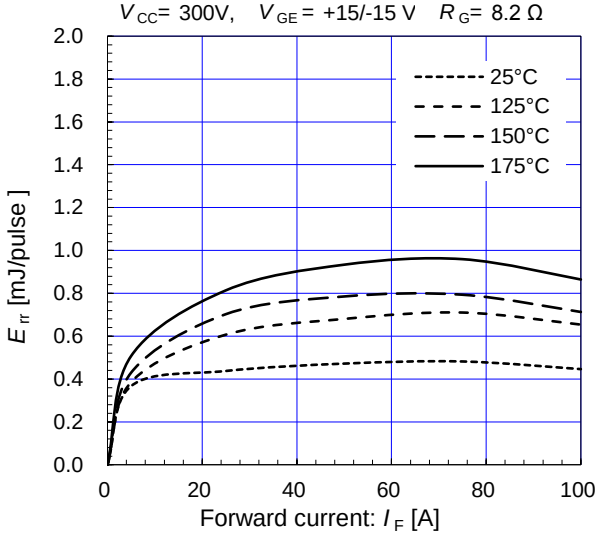
V_{CC}= 300V, V_{GE} = +15/-15 V I_C= 50A



[Inverter]

E_{rr} vs. Forward current (typ.)

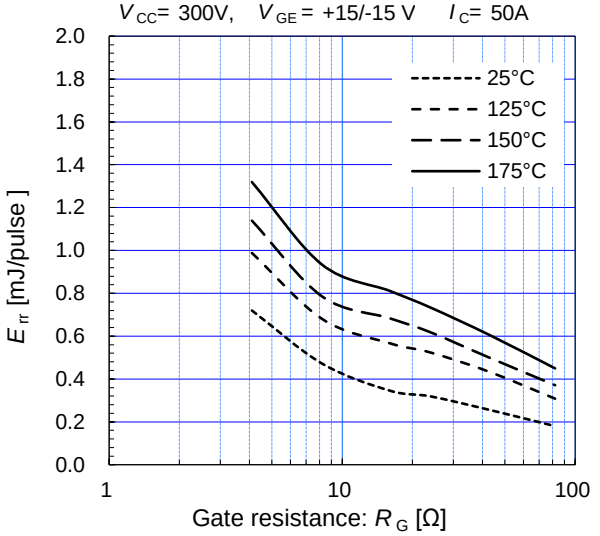
V_{CC}= 300V, V_{GE} = +15/-15 V R_G= 8.2 Ω



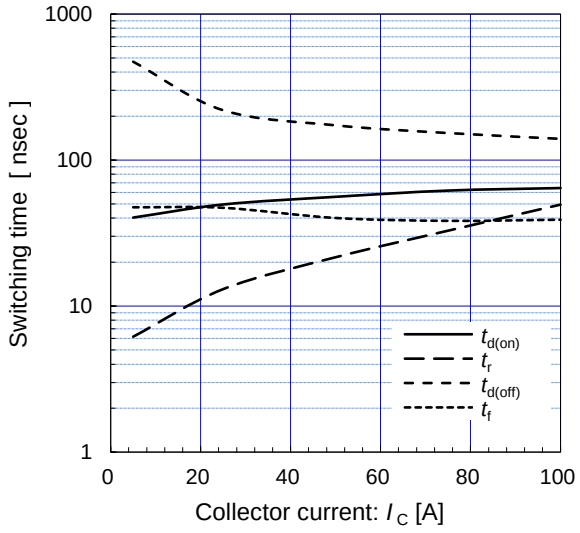
[Inverter]

E_{rr} vs. Gate resistance (typ.)

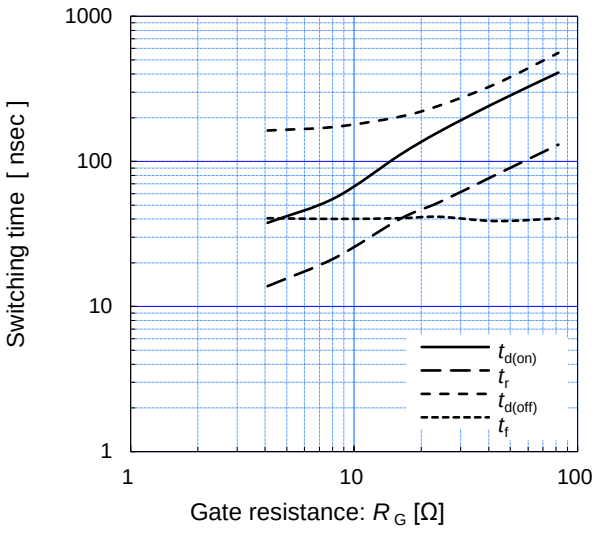
V_{CC}= 300V, V_{GE} = +15/-15 V I_C= 50A



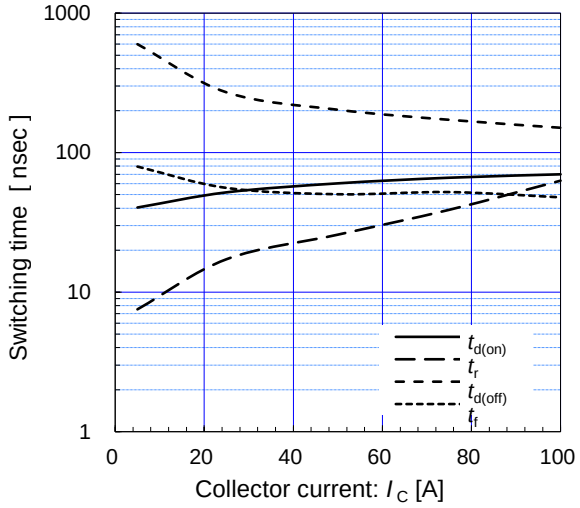
[Inverter]
Switching time vs. Collector current (typ.)
V_{CC}= 300V, R_G= 8.2Ω V_{GE}= +15/-15 V, T_{vj}= 25°C



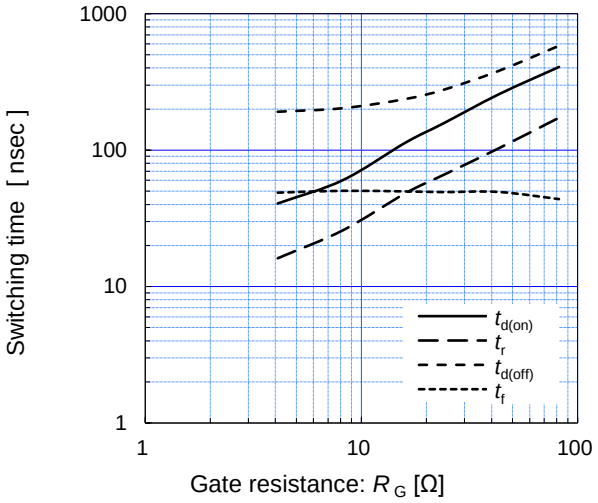
[Inverter]
Switching time vs. Gate resistance (typ.)
V_{CC}= 300V, I_C= 50A, V_{GE}= +15/-15 V, T_{vj}= 25°C



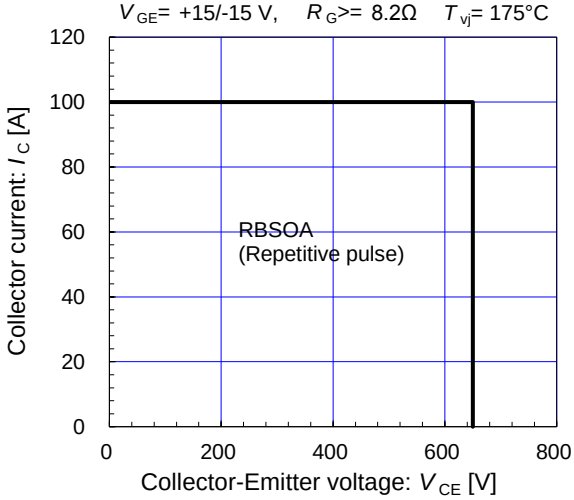
[Inverter]
Switching time vs. Collector current (typ.)
V_{CC}= 300V, R_G= 8.2Ω V_{GE}= +15/-15 V, T_{vj}= 175°C



[Inverter]
Switching time vs. Gate resistance (typ.)
V_{CC}= 300V, I_C= 50A, V_{GE}= +15/-15 V, T_{vj}= 175°C



[Inverter]
Reverse bias safe operating area (max.)
V_{GE}= +15/-15 V, R_G>= 8.2Ω T_{vj}= 175°C

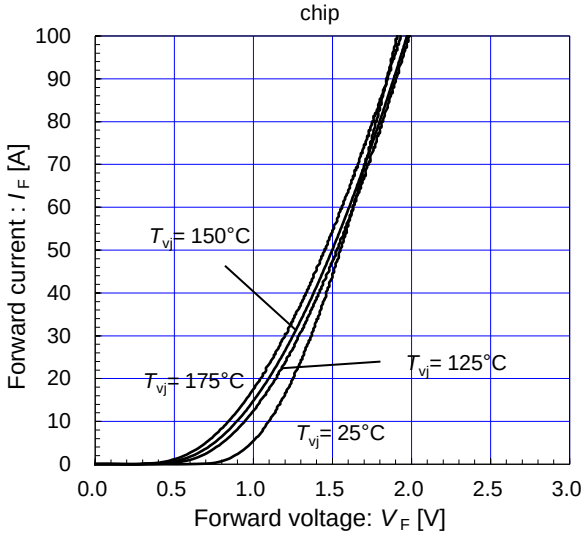


(Main terminals)

[Inverter]

Forward current vs. Forward voltage (typ.)

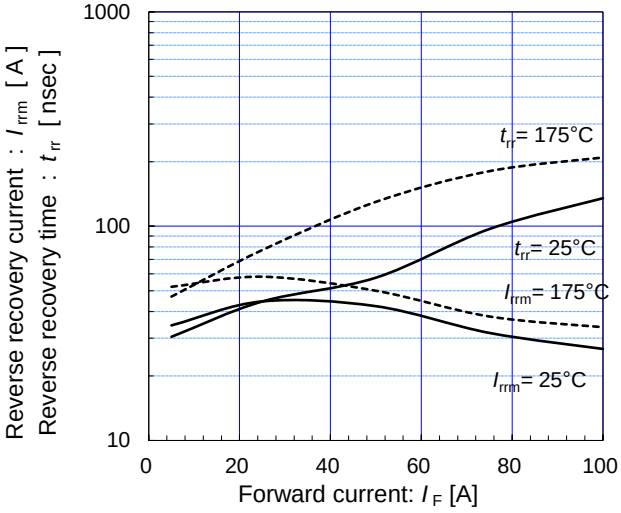
chip



[Inverter]

Reverse recovery characteristics (typ.)

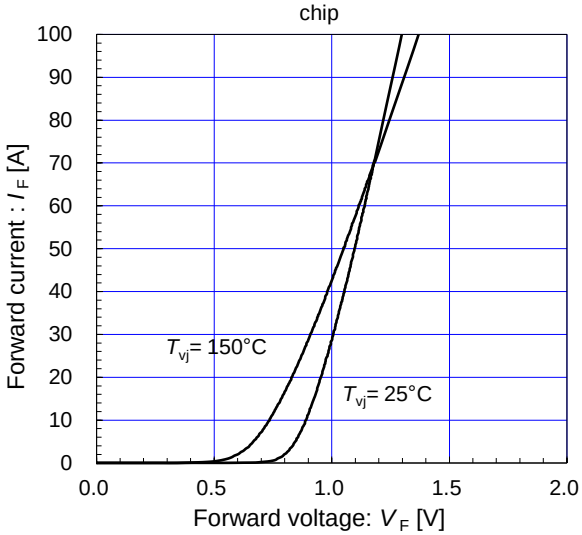
V_{CC}= 300V, V_{GE}= +15/-15 V, R_G= 8.2Ω



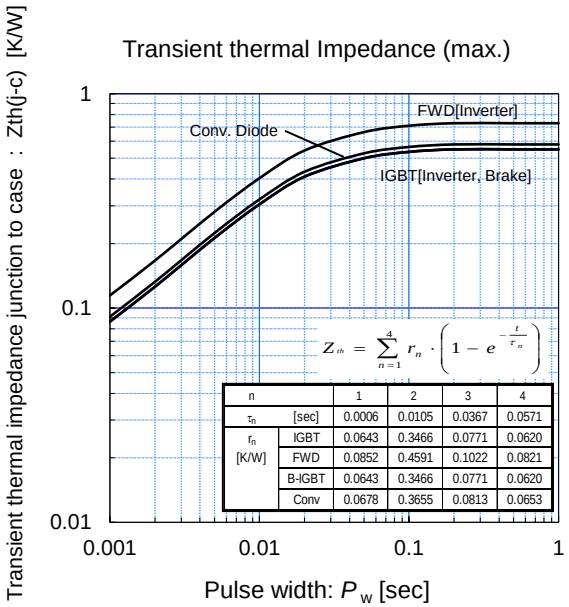
[Converter]

Forward current vs. Forward voltage (typ.)

chip



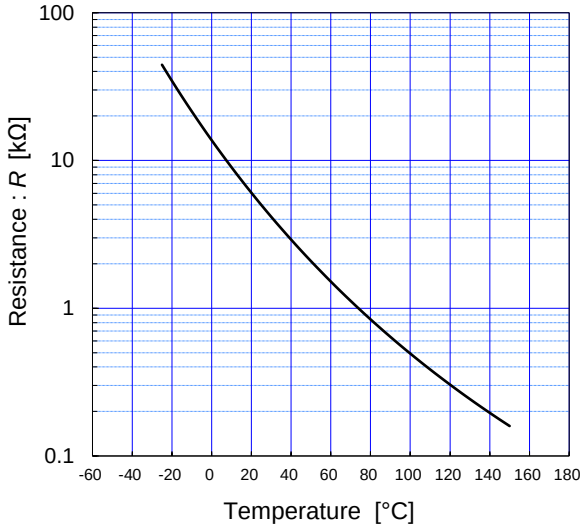
Transient thermal Impedance (max.)



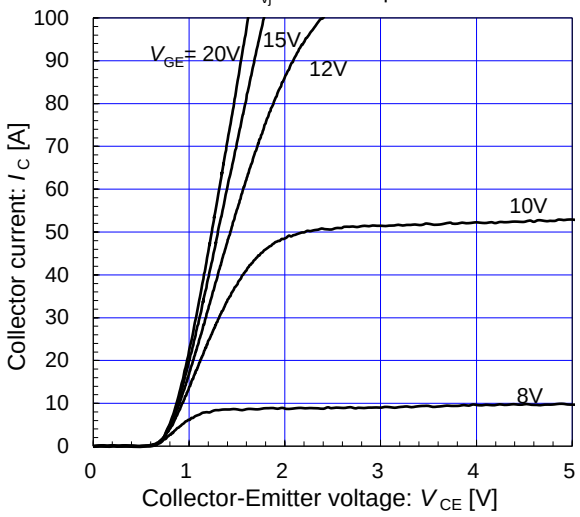
n		1	2	3	4
τ_n	[sec]	0.0006	0.0105	0.0367	0.0571
r_n [K/W]	IGBT	0.0643	0.3466	0.0771	0.0620
	FWD	0.0852	0.4591	0.1022	0.0821
	B-IGBT	0.0643	0.3466	0.0771	0.0620
	Conv	0.0678	0.3655	0.0813	0.0653

[Thermistor]

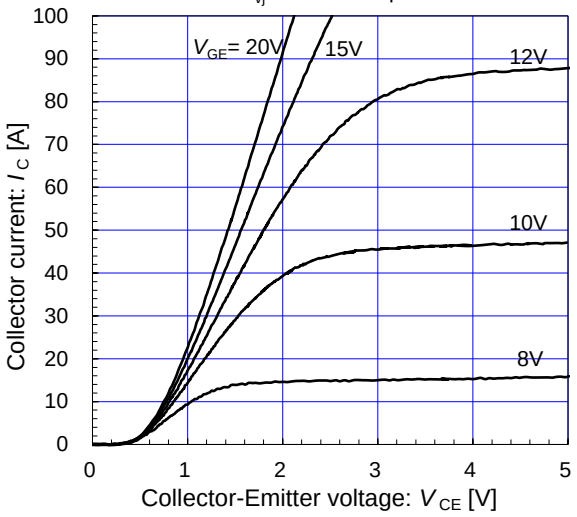
Temperature characteristic (typ.)



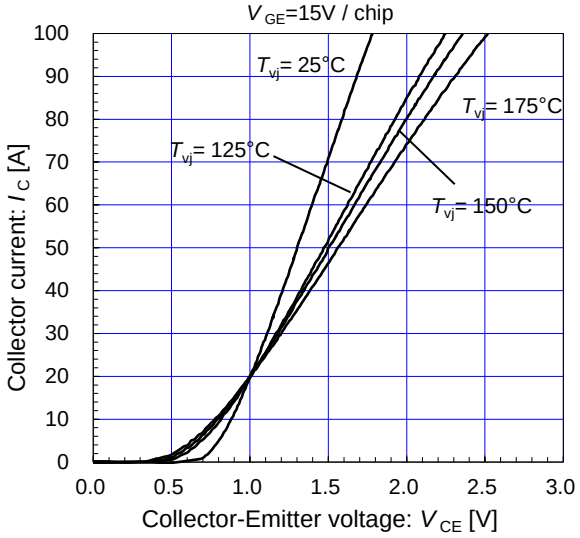
[Brake]
Collector current vs. Collector-Emitter voltage (typ.)
T_{vj}= 25°C / chip



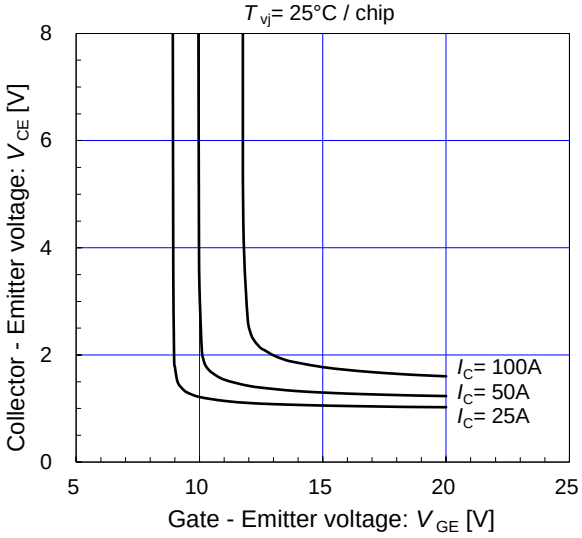
[Brake]
Collector current vs. Collector-Emitter voltage (typ.)
T_{vj}= 175°C / chip



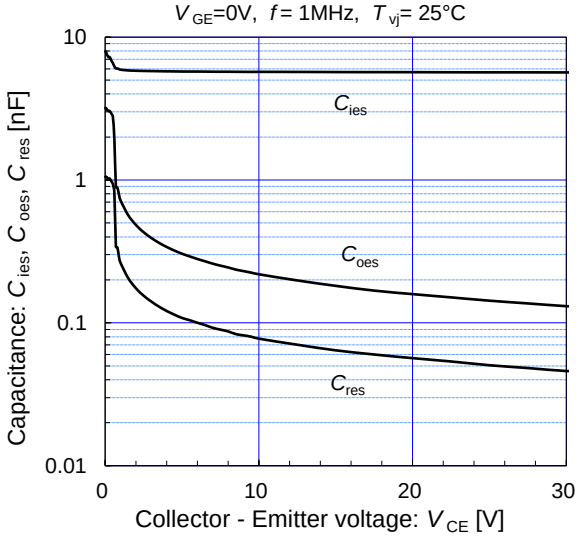
[Brake]
Collector current vs. Collector-Emitter voltage (typ.)
V_{GE}=15V / chip



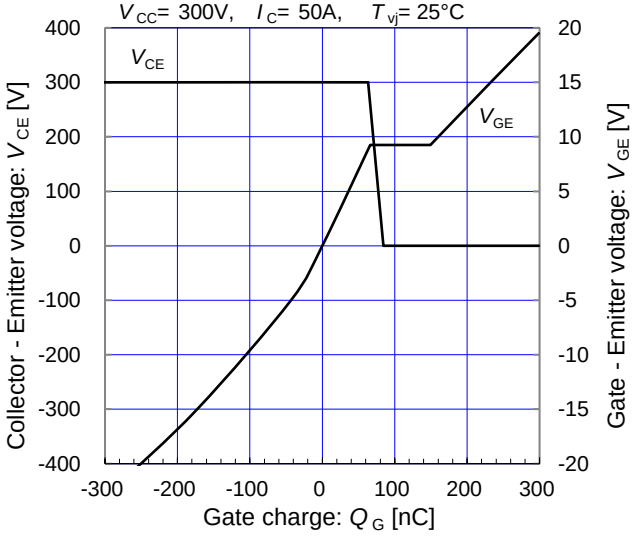
[Brake]
Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)
T_{vj}= 25°C / chip



[Brake]
Capacitance vs. Collector-Emitter voltage (typ.)
V_{GE}=0V, f= 1MHz, T_{vj}= 25°C



[Brake]
Dynamic Gate charge (typ.)
V_{CC}= 300V, I_C= 50A, T_{vj}= 25°C



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1. This Catalog contains the product specifications, characteristics, data, materials, and structures as of 12/2017.
The contents are subject to change without notice for specification changes or other reasons. When using a product listed in this Catalog, be sure to obtain the latest specifications.

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4. The products introduced in this Catalog are intended for use in the following electronic and electrical equipment which has normal reliability requirements.
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・Machine tools ・Audiovisual equipment ・Electrical home appliances ・Personal equipment ・Industrial robots etc.

5. If you need to use a product in this Catalog for equipment requiring higher reliability than normal, such as for the equipment listed below, it is imperative to contact Fuji Electric Co., Ltd. to obtain prior approval. When using these products for such equipment, take adequate measures such as a backup system to prevent the equipment from malfunctioning even if a Fuji's product incorporated in the equipment becomes faulty.
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・Emergency equipment for responding to disasters and anti-burglary devices ・Safety devices ・Medical equipment

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7.

8. If you have any question about any portion in this Catalog, ask Fuji Electric Co., Ltd. or its sales agents before using the product. Neither Fuji Electric Co., Ltd. nor its agents shall be liable for any injury caused by any use of the products not in accordance with instructions set forth herein.

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